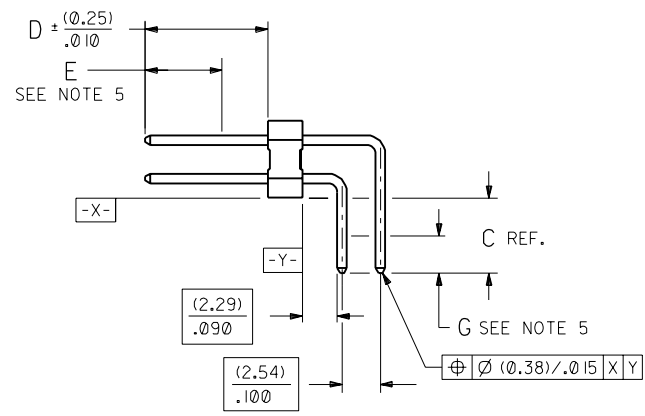
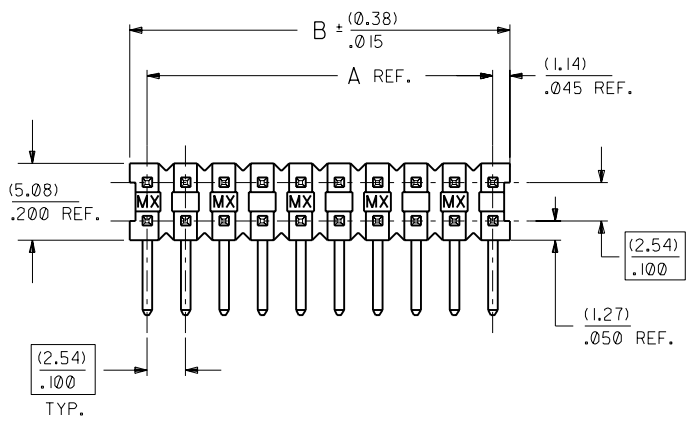


RECOMMENDED P.C. BOARD HOLE LAYOUT



CKT. SIZE	DIM. A REF.		DIM. B REF.	
	(MM)	INCH	(MM)	INCH
4	(2.54)	.100	(4.83)	.190
6	(5.08)	.200	(7.37)	.290
8	(7.62)	.300	(9.91)	.390
10	(10.16)	.400	(12.45)	.490
12	(12.70)	.500	(14.99)	.590
14	(15.24)	.600	(17.53)	.690
16	(17.78)	.700	(20.07)	.790
18	(20.32)	.800	(22.61)	.890
20	(22.86)	.900	(25.15)	.990
22	(25.40)	1.000	(27.69)	1.090
24	(27.94)	1.100	(30.23)	1.190
26	(30.48)	1.200	(32.77)	1.290
28	(33.02)	1.300	(35.31)	1.390
30	(35.56)	1.400	(37.85)	1.490
32	(38.10)	1.500	(40.39)	1.590
34	(40.64)	1.600	(42.93)	1.690
36	(43.18)	1.700	(45.47)	1.790
38	(45.72)	1.800	(48.01)	1.890
40	(48.26)	1.900	(50.55)	1.990
42	(50.80)	2.000	(53.09)	2.090
44	(53.34)	2.100	(55.63)	2.190
46	(55.88)	2.200	(58.17)	2.290
48	(58.42)	2.300	(60.71)	2.390
50	(60.96)	2.400	(63.25)	2.490
52	(63.50)	2.500	(65.79)	2.590
54	(66.04)	2.600	(68.33)	2.690
56	(68.58)	2.700	(70.87)	2.790
58	(71.12)	2.800	(73.41)	2.890
60	(73.66)	2.900	(75.95)	2.990
62	(76.20)	3.000	(78.49)	3.090
64	(78.74)	3.100	(81.03)	3.190
66	(81.28)	3.200	(83.57)	3.290
68	(83.82)	3.300	(86.11)	3.390
70	(86.36)	3.400	(88.65)	3.490
72	(88.90)	3.500	(91.19)	3.590
74	(91.44)	3.600	(93.73)	3.690
76	(93.98)	3.700	(96.27)	3.790
78	(96.52)	3.800	(98.81)	3.890
80	(99.06)	3.900	(101.35)	3.990

**NOTES:**

- PIN PUSHOUT FORCE: 4 LBS. MIN.
- FOR ILLUSTRATION PURPOSES, 20 (DUAL 10) CIRCUIT SIZE IS SHOWN.
- PINS MUST MEET SOLDERABILITY SPEC. ES-152, EXCEPT VOIDS ARE PERMISSIBLE AT BANDOLIER PIN FAYING SURFACE. (APPROX. .025 LNG X .006 WD. REF.) - 2 LOCATIONS
- WAFER TO BE FLAT WITHIN (0.03 MM/CM)/.003 IN./IN.
- MEASURE POINT FOR PLATING THICKNESS.
- THIS PRODUCT CONFORMS TO MOLEX PRODUCT SPEC. PS-70203.
- FOR ASSEMBLIES WITH VOIDS, REFER TO DRAWING NUMBER SDA-70203-5001-9999.
- PACKAGING INFORMATION: (UNLESS OTHERWISE NOTED IN TABLES)  

CIRCUIT SIZE	PACKAGING DRAWING
4 THROUGH 8	PK-70873-0353
10 AND OVER	PK-70873-0075

**FINISH:**

- 164 - .000150 MIN. TIN/LEAD PLATE OVER NICKEL PLATE.
- 571 - .000015 MIN. GOLD PLATE IN SELECT AREA, .000075 MIN. TIN/LEAD PLATE IN SELECT AREA, OVER NICKEL PLATE OVERALL.
- 574 - .000030 MIN. GOLD PLATE IN SELECT AREA, .000075 MIN. TIN/LEAD PLATE IN SELECT AREA, OVER NICKEL PLATE OVERALL.

**MATERIAL:**

- WAFER - G.F. POLYESTER; 94V-0; COLOR; BLACK
- PIN - PHOSPHOR BRONZE

C1	REVISE PKGNG ECN UDT2000-0949 SCHAFFER 00/4/6
C	REVISED PER ECN # U60711 1/8/96 BJS/RCB
B1	ADDED EDP #'S PER ECR # U60256 95/08/23 CAC
B	VOIDED EDP NO'S PER ECR # U60097 95/07/27 CAC
A	RELEASED PER ECR # U31656 11/18/93 REED

DIMENSIONS SHOWN (METRIC) INCH		UNLESS OTHERWISE SPECIFIED TOLERANCES ANGULAR ± 1/2°	
3 PLACE ± .005	INCH	---	METRIC
2 PLACE ± .01	INCH	± 0.13	METRIC
1 PLACE ---	INCH	± 0.25	METRIC
DRAWING MUST REMAIN WITHIN DIMENSIONS			
DRWG. BY: SMR	CHK'D. BY: SMR	FILE NAME: S70203X1	SCALE: 4: 1
SEE CHART		SDA-70203-0001-5000	
MFG. SH. REV. LTR.		REVISE ONLY ON CAD SYSTEM	
TITLE: SALES ASSY-DUAL ROW WAFER W/BREAK-OFF OPTION RIGHT ANGLE/.025 SQ PINS		SHEET NO. DATE: 1 OF 2 11/18/93	
PART NO. MOLEX INCORPORATED U.S.A.		DRWG. NO. U.S.A.	
DA		C	

